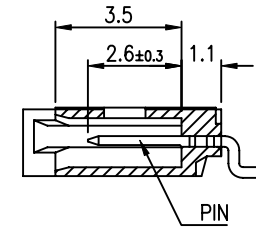
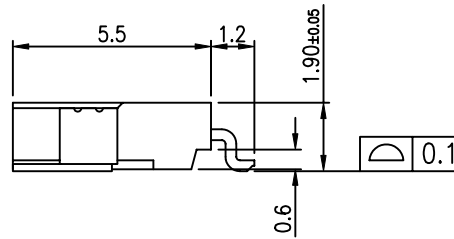
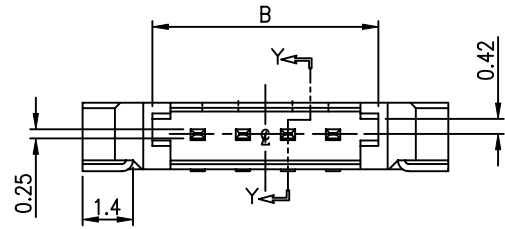
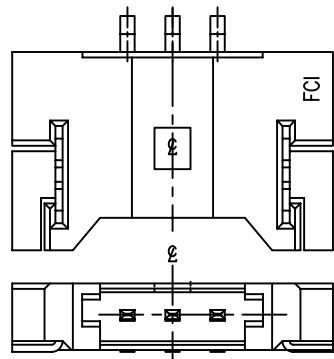


- NOTES:
- MATERIAL:
 - 1.1 HOUSING: HIGH TEMP THERMOPLASTIC,UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH 1u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - GOLD FLASH 1u" MIN. OVERALL
 - REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 - SPEC. PLS. REFER TO GS-12-573.
 - PACKAGE PLS. REFER TO GS-14-1315.
 - PART NUMBER DESCRIPTION:
 - 10089716-XXX 0 0 0 LF
 - LEAD FREE
 - COLOR
 - 0: NATURAL
 - PLATING
 - 0: GOLD FLASH

NO. OF CONTACTS
PACKING
0: TAPE & REEL



SECT. Y-Y



FOR 2 & 3 PIN

CKT	Dim.A	Dim.B	Dim.C	Dim.D
002	1.25	3.77	7.65	--
003	2.50	5.02	8.90	--
004	3.75	6.27	10.15	2.50
005	5.00	7.52	11.40	3.75
006	6.25	8.77	12.65	5.00
009	10.00	12.52	16.40	8.75

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.25	projection	title		
A	T08-1164	WL	08/11/08		.XX ± 0.15		1.25mm WIRE TO BOARD WAFER SMT R/A TYPE		
B	T08-1185	WL	11/13/08		.XXX ± 0.10				
C	T08-1196	WL	12/10/08	angles	0° ± 2°		product family		code
D	T09-1001	WL	01/05/09	dr	LEIF SHEN 06/18/08		WTB	TWN	
E	T09-1005	WL	01/20/09	enr	LEIF SHEN 06/18/08	size	dwg no	sheet	
F	T09-1077	WL	06/05/09	chr	LEIF SHEN 06/18/08	scale	10089716		1 of 1
				appd	JOSEPH HSIA 06/18/08	A4			
sheet index	revision sheet	F	1						